

Final Product Change Notification

202504018F01: Introduction of Assembly Source NXP Bangkok in Addition to NXP Kaohsiung for NCJ29D5 UWB Product Family

Note: This notice is NXP Company

Proprietary.

Issue Date: Oct 06, 2025 Effective Date: Jan 04, 2026

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Management summary

NXP Bangkok (ATBK) will be introduced as assembly source for NCJ29D5 UWB product family in addition to NXP Kaohsiung (ATKH) to support the demand for supply chain flexibility.

Change Category

[]water Fab [X]Assembly []Packing/Shipping/Labeling [X] Lest	Matchais	Materials		[]Test Equipment	[]Errata
	[]Wafer Fab Location	[X]Assembly Location	[]Packing/Shipping/Labeling	[X]Test Location	spec./Test

[X]Firmware []Other

Notification Overview

Description

Assembly site NXP Bangkok (ATBK) has been qualified in addition to incumbent assembly site Kaohsiung (ATKH) for NCJ29D5 UWB product family.

Furthermore, the package composition for the incumbent site will be slightly adapted for standardization and upgrade.

This adjustment contributes to attaining an improved Moisture Sensitivity Level 1 classification. The package geometry and outer dimensions remain unchanged, same holds for silicon die and product specification.

For details of the change and its qualification, see attached report.

Only for NCJ29D5BHN/00200, NCJ29D5CHN/00200, NCJ29D5DHN/00200:

The Firmware version 00200 of these NCJ29D5 (Ranger4) components will be replaced by Firmware version 00201.

Firmware 00201 has been announced and introduced in 2022, and product versions with that firmware are in mass production since then. Details of this change are described in attached SWUP presentation.

Reason

- Increased product demand
- Supply resilience and redundancy through dual source assembly.
- Improvement of moisture sensitivity level to MSL1, which allows higher flexibility in customer production and reduction of waste.

Identification of Affected Products

Replacement part type created, see Parts Affected list

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Dec 01, 2025

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Achieving Moisture Sensitivity Level 1 enables shipment without the need for dry pack.

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Per individual alignment with customers

Additional information

Self qualification:view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Nov 05, 2025.

Remarks

Product availability: First shipment dates will be individually aligned with customers.

Attached to this notification is a change description, a description of the firmware update (where applicable) and the ZVEI DeQuMa (both xlsm and pdf in zipped file). Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the files attached to this PCN.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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12NC	Orderable Part Number	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	New 12NC	New Orderable Part Number	New Product Type	New Product Description	Product Line N	Notes
935430452518	NCJ29D5BHN/00201Y	NCJ29D5BHN/00201	UWB	H(V)QFN40WF	SOT618-7(DD)	RFS	No	935464881118	NCJ29D5BHN/00201/J	NCJ29D5BHN/00201/D	UWB	BLC1	
935430453518	NCJ29D5CHN/00201Y	NCJ29D5CHN/00201	UWB	H(V)QFN40WF	SOT618-7(DD)	RFS	No	935464885118	NCJ29D5CHN/00201AJ	NCJ29D5CHN/00201/D	UWB	BLC1	
935430434518	NCJ29D5DHN/00201Y	NCJ29D5DHN/00201	UWB	H(V)QFN40WF	SOT618-7(DD)	RFS	No	935464541118	NCJ29D5DHN/00201AJ	NCJ29D5DHN/00201/D	UWB	BLC1	
935395735518	NCJ29D5BHN/00200Y	NCJ29D5BHN/00200	UWB	H(V)QFN40WF	SOT618-7(DD)	RFS	No	935464881118	NCJ29D5BHN/00201/J	NCJ29D5BHN/00201/D	UWB	BLC1	
935395744518	NCJ29D5CHN/00200Y	NCJ29D5CHN/00200	UWB	H(V)QFN40WF	SOT618-7(DD)	RFS	No	935464885118	NCJ29D5CHN/00201AJ	NCJ29D5CHN/00201/D	UWB	BLC1	
935397901518	NCJ29D5DHN/00200Y	NCJ29D5DHN/00200	UWB	H(V)QFN40WF	SOT618-7(DD)	RFS	No	935464541118	NCJ29D5DHN/00201AJ	NCJ29D5DHN/00201/D	UWB	BLC1	